

TOSHIBA

Surface Mount LED

TLOE1005B

Features

3.2 (L) x 2.4 (W) x 2.4 (H) mm
 2 mm lens top type
 InGaAlP LED
 Reflow soldering is possible
 Standard embossed taping 4 mm pitch : T03 (1000 pcs/reel)

Applications

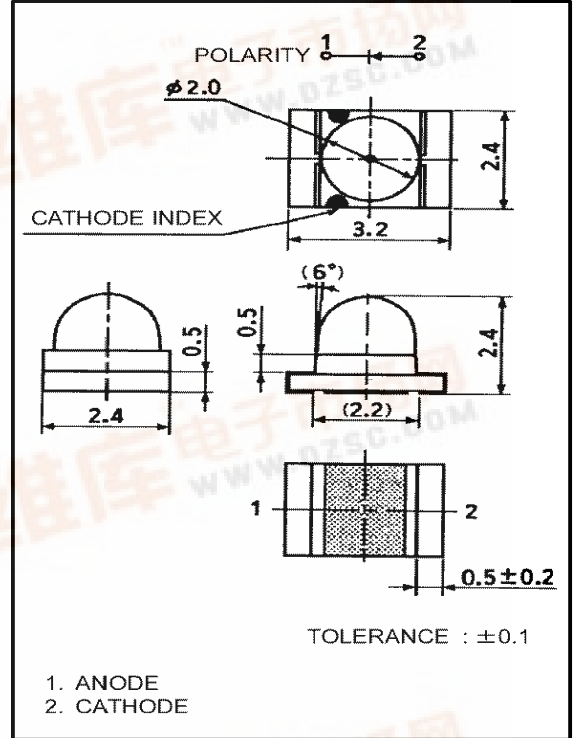
High-output backlighting source
 Battery-powered equipment
 Message boards
 Portable devices
 Computer peripherals

Maximum Ratings (Ta=25°C)

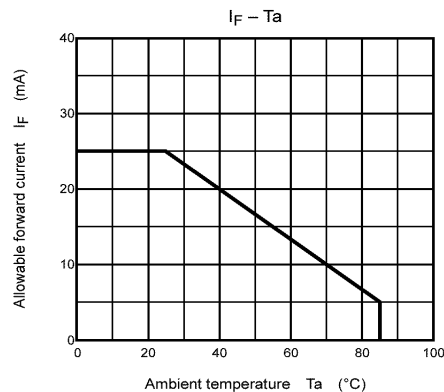
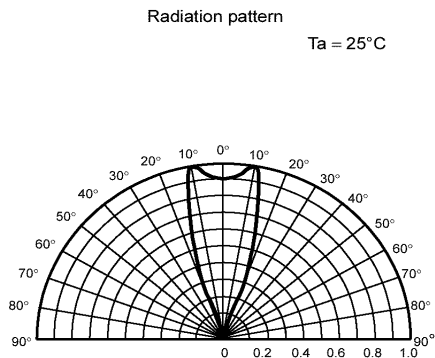
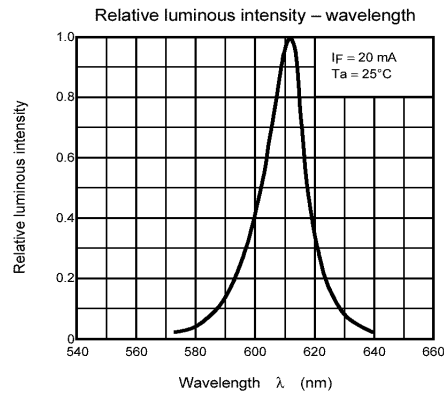
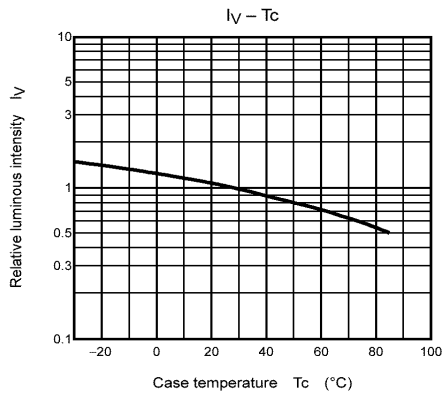
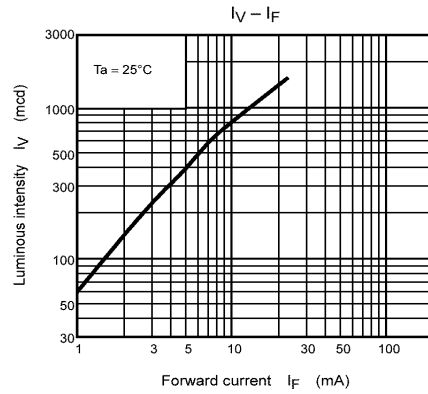
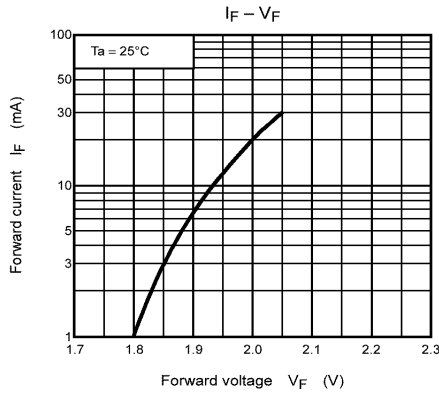
Characteristic	Symbol	Max.	Unit
Forward Current	I _F	25	mA
Reverse Voltage	V _R	4.00	V
Power Dissipation	P _D	60.00	mW
Operating Temperature	T _{opr}	-40 ~ 85	°C
Storage Temperature	T _{stg}	-40 ~ 100	°C
Soldering Temperature	T _{sol}	260	°C
Soldering Time	-	for 3 sec. max	-

Opto-Electrical Characteristics (Ta=25°C)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage	V _F	I _F =20mA	-	2.00	2.40	V
Reverse Current	I _R	V _R =4V	-	-	50	µA
Luminous Intensity	I _v	I _F =20mA	476.00	1500.00	-	mcd
Viewing Angle	2θ ^{1/2}	-	-	45°	-	deg.
Peak Wavelength	λ _p	I _F =20mA	-	612	-	nm
Dominant Wavelength	λ _d	I _F =20mA	-	605	-	nm
Spectral Line Half Width	Δλ	I _F =20mA	-	15	-	nm



TLOE1005B Graphs



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